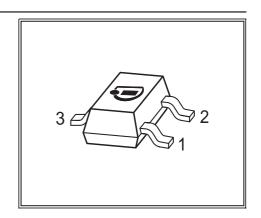


#### **NPN Silicon RF Transistor**

- For linear broadband amplifier application up to 500 MHz
- SAW filter driver in TV tuners
- Pb-free (RoHS compliant) package 1)
- Qualified according AEC Q101







Туре	Marking	Pin Configuration Package			Package
BF799	LKs	1 = B	2 = E	3 = C	SOT23

### **Maximum Ratings**

Parameter	Symbol	Value	Unit	
Collector-emitter voltage	$V_{\sf CEO}$	20	V	
Collector-emitter voltage	$V_{CES}$	30		
Collector-base voltage	$V_{\mathrm{CBO}}$	30		
Emitter-base voltage	$V_{EBO}$	3		
Collector current	I <sub>C</sub>	35	mA	
Peak collector current,	I <sub>CM</sub>	50		
Peak base current	I <sub>BM</sub>	15		
Total power dissipation	P <sub>tot</sub>	280	mW	
$T_{\rm S} \le 69  ^{\circ}{\rm C}^{2)}$				
Junction temperature	$T_{i}$	150	°C	
Storage temperature	$T_{\rm stq}$	-65 150		

#### **Thermal Resistance**

Junction - soldering point <sup>3)</sup>	R <sub>thJS</sub>	≤ 290	K/W

<sup>&</sup>lt;sup>1</sup>Pb-containing package may be available upon special request

 $<sup>^2</sup>T_{\mbox{\scriptsize S}}$  is measured on the collector lead at the soldering point to the pcb

 $<sup>^3</sup>$ For calculation of  $R_{ ext{thJA}}$  please refer to Application Note Thermal Resistance

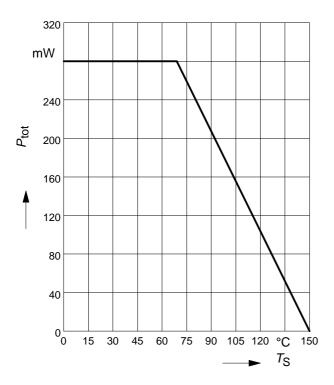


**Electrical Characteristics** at  $T_A$  = 25 °C, unless otherwise specified.

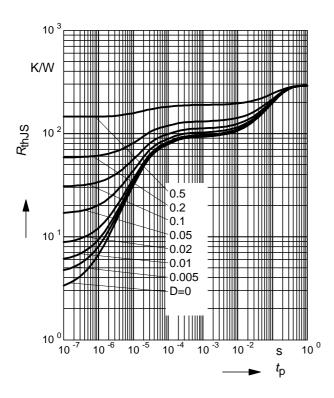
Parameter	Symbol	Values			Unit
		min.	typ.	max.	1
DC characteristics			•		
Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>	20	-	-	V
$I_{\rm C} = 1 \text{ mA}, I_{\rm B} = 0$					
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>	30	-	-	
$I_{\rm C} = 10 \ \mu {\rm A}, \ I_{\rm E} = 0$					
Base-emitter breakdown voltage	V <sub>(BR)EBO</sub>	3	-	-	
$I_{\rm E} = 10 \ \mu {\rm A}, \ I_{\rm C} = 0$					
Collector-base cutoff current	I <sub>CBO</sub>	-	-	100	nA
$V_{\text{CB}} = 20 \text{ V}, I_{\text{E}} = 0$					
DC current gain	h <sub>FE</sub>				-
$I_{\rm C} = 5 \text{ mA}, \ V_{\rm CE} = 10 \text{ V}$		35	95	-	
$I_{\rm C} = 20 \text{ mA}, \ V_{\rm CE} = 10 \text{ V}$		40	100	250	
Collector-emitter saturation voltage	V <sub>CEsat</sub>	-	0.1	0.3	V
$I_{\rm C} = 20 \text{ mA}, I_{\rm B} = 2 \text{ mA}$					
Base-emitter saturation voltage	V <sub>BEsat</sub>	-	-	0.95	
$I_{\rm C} = 20 \text{ mA}, I_{\rm B} = 2 \text{ mA}$					
AC characteristics					
Transition frequency	f <sub>T</sub>				MHz
$I_{\rm C} = 5$ mA, $V_{\rm CE} = 10$ V, $f = 100$ MHz		-	800	-	
$I_{C} = 20 \text{ mA}, \ V_{CE} = 8 \text{ V}, \ f = 100 \text{ MHz}$		-	1100	-	
Output capacitance	Cob	-	0.96	-	pF
$V_{CB} = 10 \text{ V}, I_{E} = 0 \text{ mA}, f = 1 \text{ MHz}$					
Collector-base capacitance	C <sub>cb</sub>	-	0.7	-	
$V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$					
Collector-emitter capacitance	C <sub>ce</sub>	-	0.28	-	
$V_{CE} = 10 \text{ V}, f = 1 \text{ MHz}$					
Noise figure	F	-	3	-	dB
$I_{C} = 5 \text{ mA}, \ V_{CE} = 10 \text{ V}, \ f = 100 \text{ MHz},$					
$Z_{\rm S} = 50 \ \Omega$					
Output conductance	<i>g</i> 22e	-	60	-	μS
$I_{C} = 20 \text{ mA}, \ V_{CE} = 10 \text{ V}, \ f = 35 \text{ MHz}$					



# Total power dissipation $P_{tot} = f(T_S)$

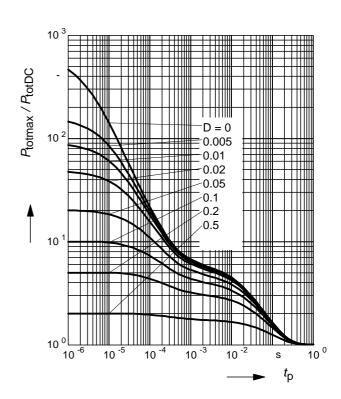


# Permissible Pulse Load $R_{thJS} = f(t_p)$



# **Permissible Pulse Load**

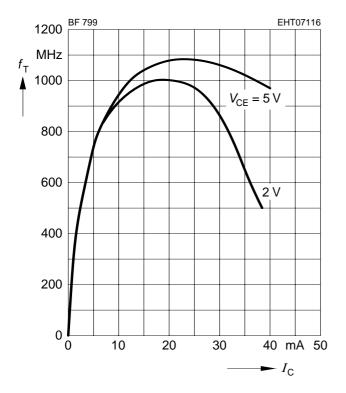
$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_{p})$$



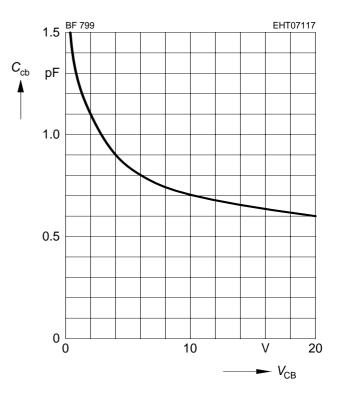


# Transition frequency $f_T = f(I_C)$

*f* = 100MHz



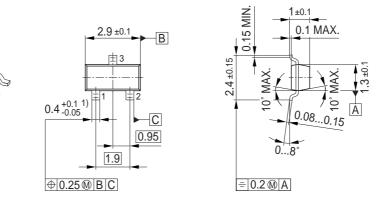
# Collector-base capacitance $C_{cb} = f(V_{CB})$ f = 1 MHz



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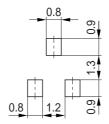


## Package Outline

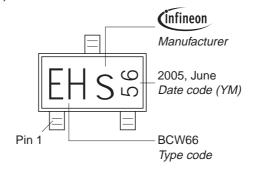


1) Lead width can be 0.6 max. in dambar area

### Foot Print

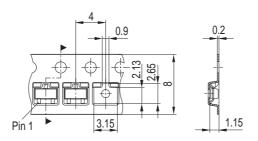


## Marking Layout (Example)



# Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel



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2007-04-20